BUK753R4-30B; BUK763R4-30B

N-channel TrenchMOS standard level FET

Rev. 01 — 5 January 2006 Product data sheet

1. Product profile

1.1 General description

N-channel enhancement mode field-effect power transistor in a plastic package using Philips High-Performance Automotive (HPA) TrenchMOS technology.

1.2 Features

- TrenchMOS technology
- 175 °C rated
- Q101 compliant
- Standard level compatible

1.3 Applications

- Automotive systems
- Motors, lamps and solenoids
- 12 V loads
- General purpose power switching

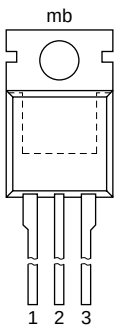
1.4 Quick reference data

- $E_{DS(AL)S} \leq 1.3$ J
- $I_D \leq 75$ A
- $R_{DSon} = 2.9$ mΩ (typ)
- $P_{tot} \leq 255$ W

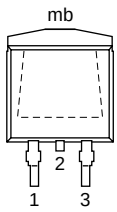
2. Pinning information

Table 1: Pinning

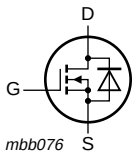
Pin	Description	Simplified outline	Symbol
1	gate (G)		
2	drain (D)		
3	source (S)		
mb	mounting base; connected to drain (D)		



SOT78 (TO-220AB)



SOT404 (D2PAK)



PHILIPS

3. Ordering information

Table 2: Ordering information

Type number	Package		
	Name	Description	Version
BUK753R4-30B	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78
BUK763R4-30B	D2PAK	plastic single-ended surface mounted package (D2PAK); 3 leads (one lead cropped)	SOT404

4. Limiting values

Table 3: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

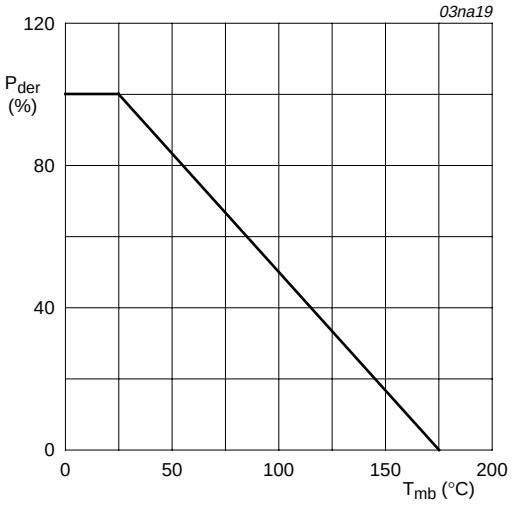
Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage			-	30	V
V_{DGR}	drain-gate voltage (DC)	R_{GS} = 20 kΩ		-	30	V
V_{GS}	gate-source voltage			-	±20	V
I_D	drain current	T_{mb} = 25 °C; V_{GS} = 10 V; Figure 2 and Figure 3	[1] [2]	-	198	A
			[3]	-	75	A
		T_{mb} = 100 °C; V_{GS} = 10 V; Figure 2	[3]	-	75	A
I_{DM}	peak drain current	T_{mb} = 25 °C; pulsed; $t_p \leq 10$ µs; Figure 3		-	794	A
P_{tot}	total power dissipation	T_{mb} = 25 °C; Figure 1		-	255	W
T_{stg}	storage temperature			–55	+175	°C
T_j	junction temperature			–55	+175	°C
Source-drain diode						
I_{DR}	reverse drain current	T_{mb} = 25 °C	[1] [2]	-	198	A
			[3]	-	75	A
I_{DRM}	peak reverse drain current	T_{mb} = 25 °C; pulsed; $t_p \leq 10$ µs		-	794	A
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	unclamped inductive load; I_D = 75 A; $V_{DS} \leq 30$ V; R_{GS} = 50 Ω; V_{GS} = 10 V; starting at T_j = 25 °C		-	1.3	J
$E_{DS(AL)R}$	repetitive drain-source avalanche energy			-	[4]	-

[1] Current is limited by power dissipation chip rating.

[2] Refer to document *9397 750 12572* for further information.

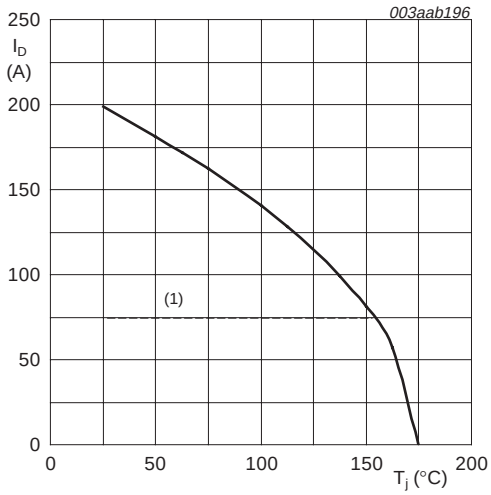
[3] Continuous current is limited by package.

[4] Max value not quoted. Repetitive rating defined in Figure 16.
Single-shot avalanche rating limited by $T_{j(max)}$ of 175 °C.
Repetitive avalanche rating limited by an average T_j of 170 °C.
Refer to application note *AN10273* for further information.



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\,\%$$

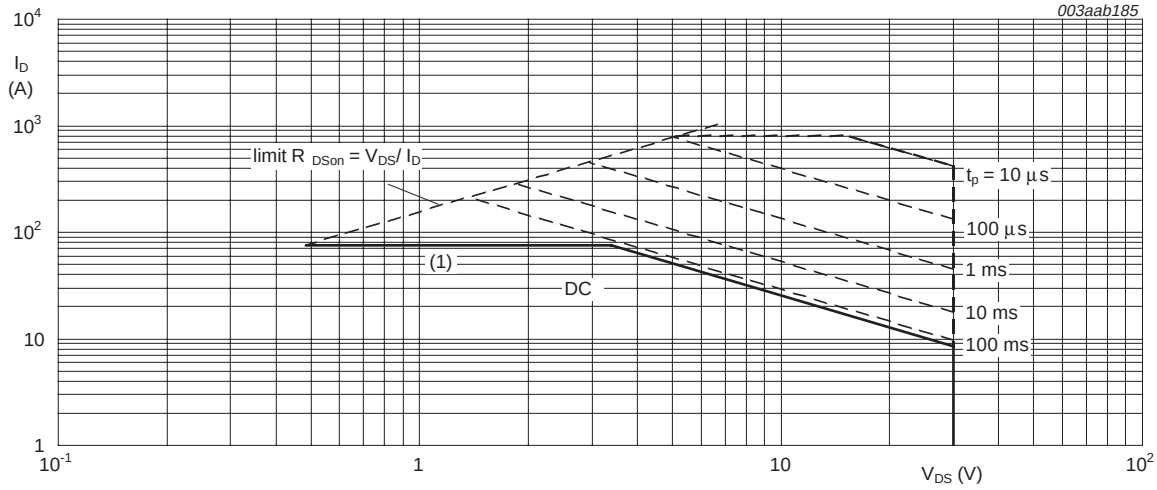
Fig 1. Normalized total power dissipation as a function of mounting base temperature



$V_{GS} \geq 5$ V

(1) Capped at 75 A due to package.

Fig 2. Continuous drain current as a function of mounting base temperature



T_{mb} = 25 °C; I_{DM} is single pulse

(1) Capped at 75 A due to package.

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

5. Thermal characteristics

Table 4: Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base		-	-	0.59	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient					
	SOT78 (TO-220AB)	vertical in free air	-	60	-	K/W
	SOT404 (D2PAK)	mounted on a printed-circuit board; minimum footprint; vertical in still air	-	50	-	K/W

5.1 Transient thermal impedance

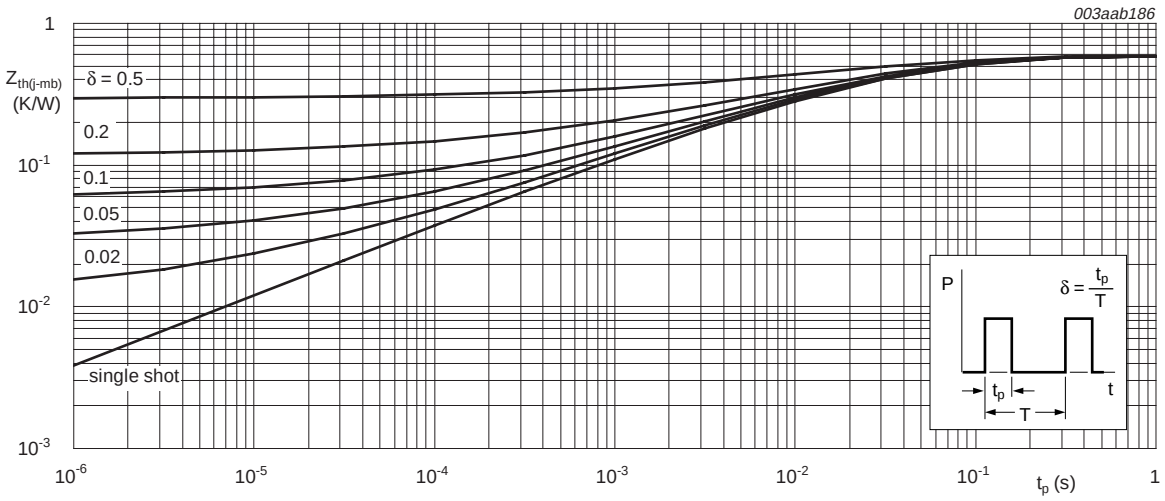


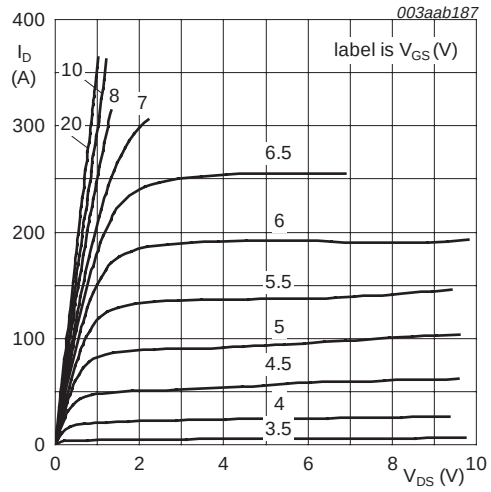
Fig 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

6. Characteristics

Table 5: Characteristics

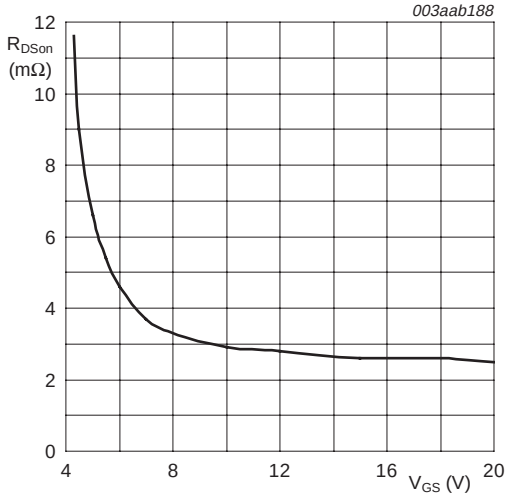
T_j = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 250 µA; V_{GS} = 0 V				
		T_j = 25 °C	30	-	-	V
		T_j = –55 °C	27	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA; V_{DS} = V_{GS}; Figure 9 and Figure 10				
		T_j = 25 °C	2	3	4	V
		T_j = 175 °C	1	-	-	V
		T_j = –55 °C	-	-	4.4	V
I_{DSS}	drain leakage current	V_{DS} = 30 V; V_{GS} = 0 V				
		T_j = 25 °C	-	0.05	10	µA
		T_j = 175 °C	-	-	500	µA
I_{GSS}	gate leakage current	V_{GS} = ±20 V; V_{DS} = 0 V	-	2	100	nA
R_{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 25 A; Figure 6 and Figure 8				
		T_j = 25 °C	-	2.9	3.4	mΩ
		T_j = 175 °C	-	-	6.5	mΩ
Dynamic characteristics						
$Q_{G(tot)}$	total gate charge	I_D = 25 A; V_{DD} = 24 V; V_{GS} = 10 V; Figure 14	-	75	-	nC
Q_{GS}	gate-source charge		-	19	-	nC
Q_{GD}	gate-drain charge		-	23	-	nC
C_{iss}	input capacitance	V_{GS} = 0 V; V_{DS} = 25 V; f = 1 MHz; Figure 12	-	3713	4951	pF
C_{oss}	output capacitance		-	1249	1499	pF
C_{rss}	reverse transfer capacitance		-	460	630	pF
$t_{d(on)}$	turn-on delay time	V_{DS} = 30 V; R_L = 1.2 Ω; V_{GS} = 10 V; R_G = 10 Ω	-	32	-	ns
t_r	rise time		-	64	-	ns
$t_{d(off)}$	turn-off delay time		-	89	-	ns
t_f	fall time		-	71	-	ns
L_D	internal drain inductance	from drain lead 6 mm from package to center of die	-	4.5	-	nH
		from contact screw on mounting base to center of die	-	3.5	-	nH
		from upper edge of drain mounting base to center of die SOT404	-	2.5	-	nH
L_S	internal source inductance	from source lead to source bond pad	-	7.5	-	nH
Source-drain diode						
V_{SD}	source-drain voltage	I_S = 25 A; V_{GS} = 0 V; Figure 15	-	0.85	1.2	V
t_{rr}	reverse recovery time	I_S = 20 A; dI_S/dt = –100 A/µs; V_{GS} = 0 V; V_R = 30 V	-	70	-	ns
Q_r	recovered charge		-	58	-	nC



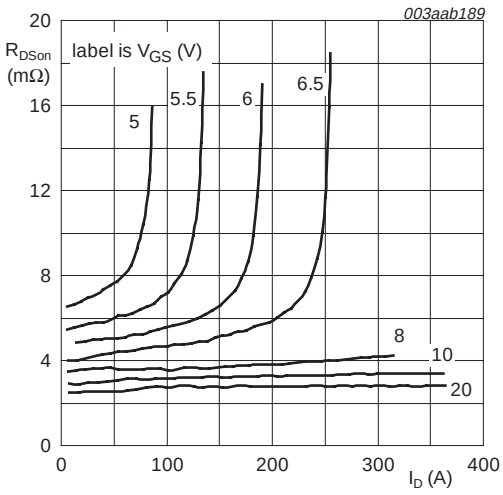
T_j = 25 °C

Fig 5. Output characteristics: drain current as a function of drain-source voltage; typical values



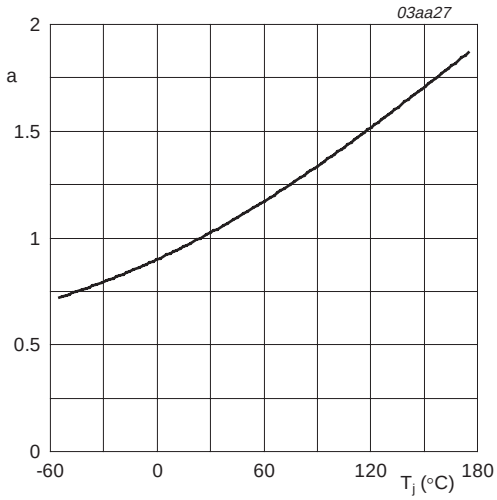
T_j = 25 °C; I_D = 25 A

Fig 6. Drain-source on-state resistance as a function of gate-source voltage; typical values



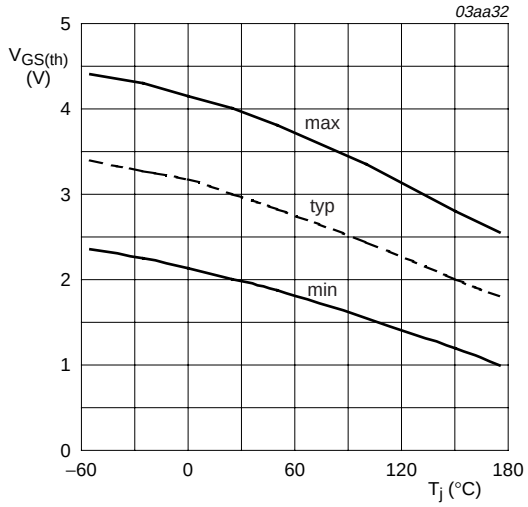
T_j = 25 °C

Fig 7. Drain-source on-state resistance as a function of drain current; typical values



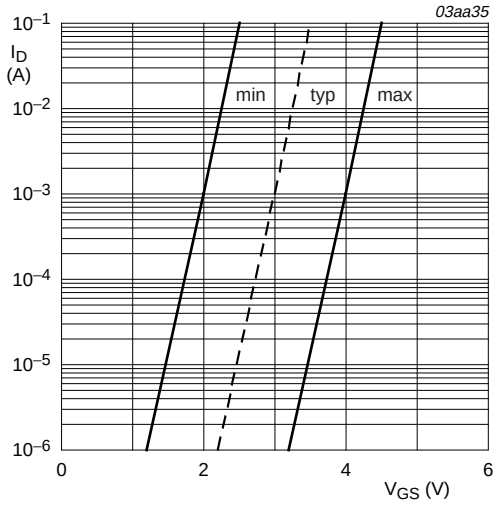
$$a = \frac{R_{DSon}}{R_{DSon(25^{\circ}C)}}$$

Fig 8. Normalized drain-source on-state resistance factor as a function of junction temperature



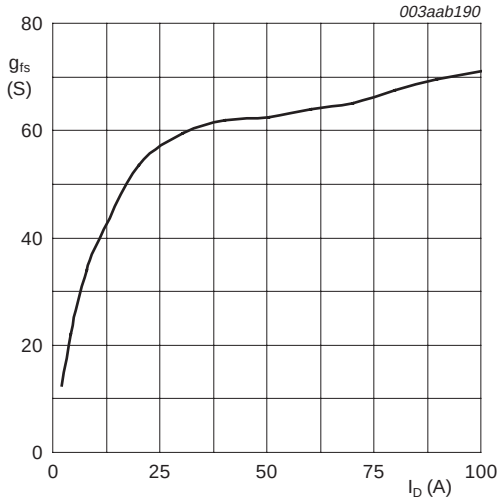
I_D = 1 mA; V_{DS} = V_{GS}

Fig 9. Gate-source threshold voltage as a function of junction temperature



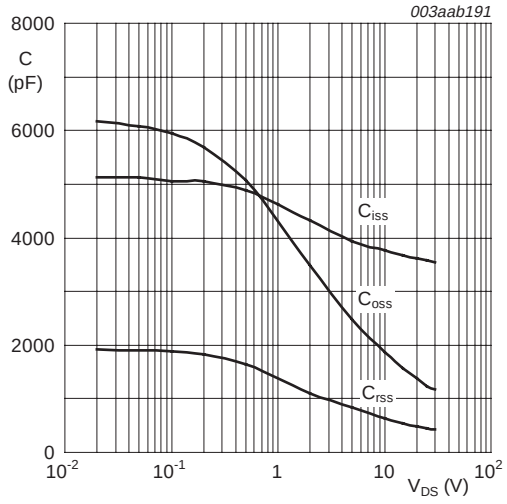
T_j = 25 °C; V_{DS} = V_{GS}

Fig 10. Sub-threshold drain current as a function of gate-source voltage



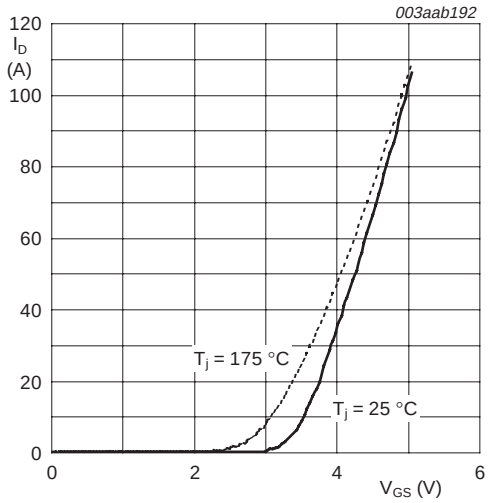
T_j = 25 °C; V_{DS} = 25 V

Fig 11. Forward transconductance as a function of drain current; typical values



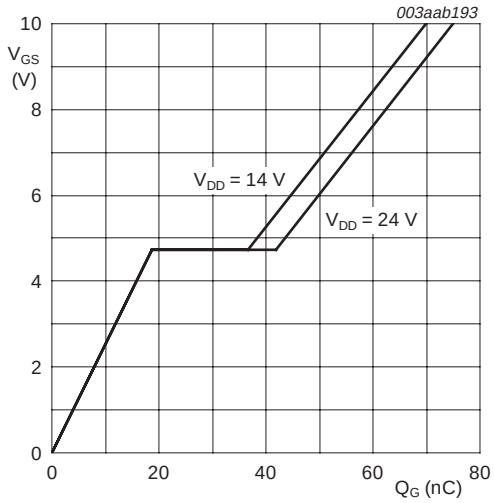
V_{GS} = 0 V; f = 1 MHz

Fig 12. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



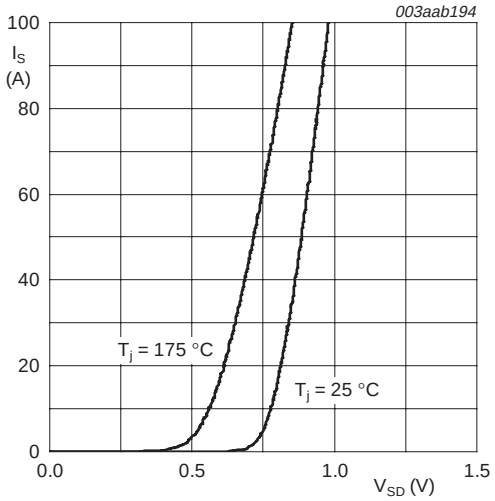
V_{DS} = 25 V

Fig 13. Transfer characteristics: drain current as a function of gate-source voltage; typical values



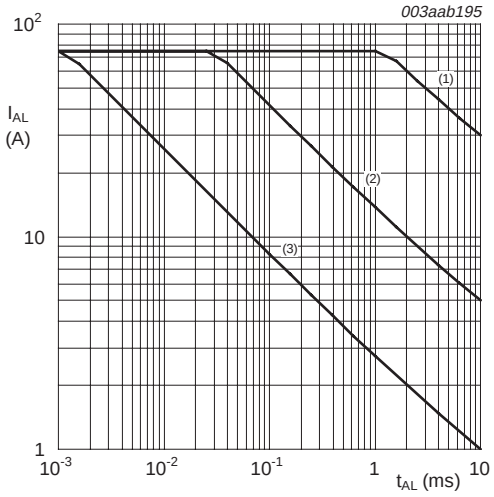
T_j = 25 °C; I_D = 25 A

Fig 14. Gate-source voltage as a function of gate charge; typical values



V_{GS} = 0 V

Fig 15. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values



See Table note 4 of Table 3 “Limiting values”

(1) Single-shot T_j = 25 °C

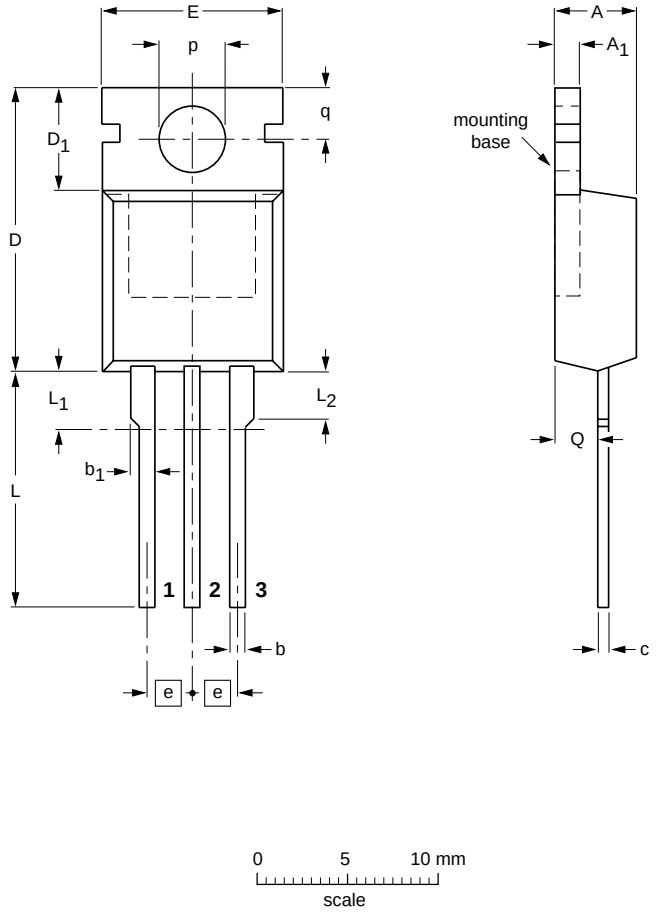
(2) Single-shot T_j = 150 °C

(3) Repetitive

Fig 16. Single-shot and repetitive avalanche rating; avalanche current as a function of avalanche time

7. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB **SOT78**



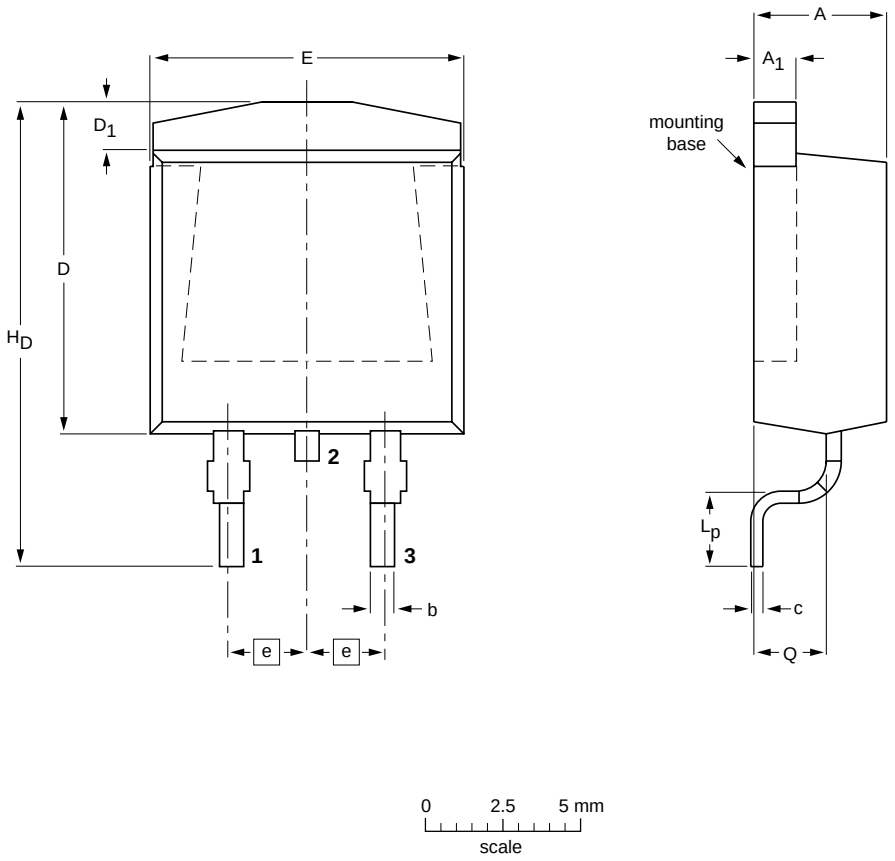
DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b	b_1	c	D	D_1	E	e	L	L_1	L_2 max.	p	q	Q
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.45 1.00	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT78		3-lead TO-220AB	SC-46			~~05-03-22~~ 05-10-25

Fig 17. Package outline SOT78 (TO-220AB)

Plastic single-ended surface mounted package (D2PAK); 3 leads (one lead cropped) **SOT404**



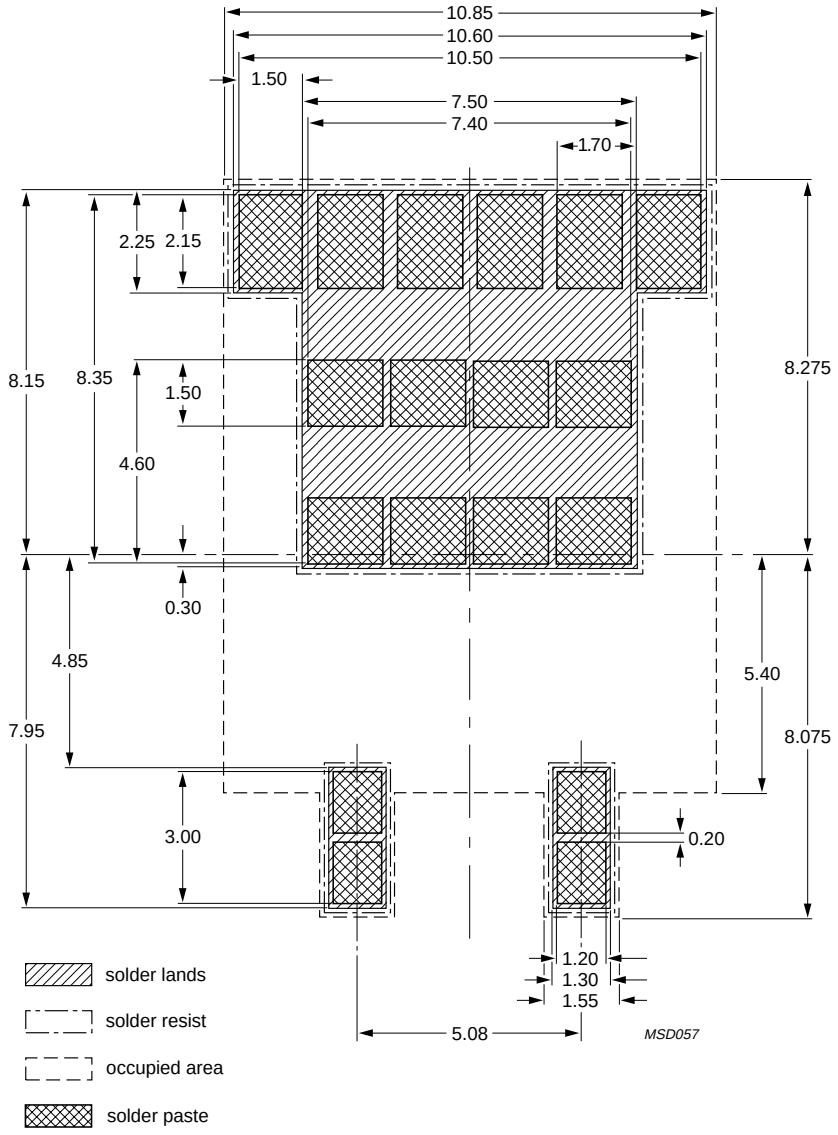
DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b	c	D max.	D_1	E	e	L_p	H_D	Q
mm	4.50 4.10	1.40 1.27	0.85 0.60	0.64 0.46	11	1.60 1.20	10.30 9.70	2.54	2.90 2.10	15.80 14.80	2.60 2.20

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT404						~~04-10-13~~ 05-02-11

Fig 18. Package outline SOT404 (D2PAK)

8. Soldering



Dimensions in mm.

Fig 19. Reflow soldering footprint for SOT404

9. Revision history

Table 6: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
BUK75_763R4-30B_1	20060105	Product data sheet	-	-	-

10. Data sheet status

Level	Data sheet status [1]	Product status [2] [3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

[1] Please consult the most recently issued data sheet before initiating or completing a design.

[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

11. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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15. Contents

Date of release: 5 January 2006

Document number: BUK75_763R4-30B_1

Published in The Netherlands